

Fairchild Semiconductor Product Package Material Disclosure

Package Type	SSOT-3						
Weight of Package (grams)	1.06E-02						
Component	Material	Wt in grams	Substance or Material	Wt% in component	Wt% in Finished Product	CAS #	Parts per Million
Lead Frame	Copper alloy	3.68E-03	Copper	97.43	34.87	7440-50-8 7439-89-6 7440-66-6 7723-14-0	348680
			Iron	2.40	33.97		339719
			Zinc	0.13	0.84		8368
			Phosphorus	0.04	0.05		453
					0.01		139
Encapsulation	Epoxy	5.70E-03	Silica	71.32	54.01	1309-64-4 1314-60-9 40039-93-8 79-94-7	540074
			Resin	27.50	38.52		385181
			Antimony Compounds	2.75	14.85		148520
					1.49		14852
			Bromine Resin	1.10	0.59		5941
Plating	Lead-free Solder	3.32E-04	Tin		3.15	7440-31-5	31457
					100.00		3.15
Chip	Silicon	7.66E-04	Silicon and trace metals		7.26	7440-21-3	72578
					99.00		7.19
Die Attach	Adhesive	Eutectic					
Wire Bond	Gold Wire	7.61E-05	Gold		0.72	7440-57-5	7210
					99.99		0.72



Materials Disclosure Disclaimer

The information provided in this Materials Disclosure is, to our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company. Also, there may not be information included in this statement regarding the minute amounts of dopant and metal materials contained within the electrically active or passive devices contained within the finished product.